

L Number	Hits	Search Text	DB	Time stamp
1	2098	"deposition chamber".clm.	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:03
2	1290	"plasma chamber".clm.	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:04
3	3324	"deposition chamber".clm. "plasma chamber".clm.	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:14
4	67458	robot\$1	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:14
5	9524	third adj2 chamber	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:15
6	30	("deposition chamber".clm. "plasma chamber".clm.) and robot\$1 and (third adj2 chamber)	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:15
7	59308	tantalum "tantalum nitride"	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:16
8	5746	"native oxide" (native adj2 oxide)	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:16
9	430150	copper	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:17
10	418	(tantalum "tantalum nitride") and ("native oxide" (native adj2 oxide)) and copper	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:17
11	0	((tantalum "tantalum nitride") and ("native oxide" (native adj2 oxide)) and copper) and (("deposition chamber".clm. "plasma chamber".clm.) and robot\$1 and (third adj2 chamber))	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:17
12	23	((tantalum "tantalum nitride") and ("native oxide" (native adj2 oxide)) and copper) and ("deposition chamber".clm. "plasma chamber".clm.)	USPAT; US-PGPUB; EPO; JPO	2004/05/26 08:17